Ref/Part name	pcs/unit
C2	1
C3	1
C4	0
C21 C31	2
C41	1
C101 C151 C241 C331 C361 C391 C431	7
C281	1
C321 C551 C561	3
C341 C351	2
C371 C381	2
C372 C382	2
C373	1
C374	0
C392	1
C441 C451	2
FL1	1
J1	1
J2	0
L372 L373 L381	3
L374	0
L375	1
P1 P2	2
P3	0
P5	1
P6	0
R1 R442 R452	0
R21 R31	2
R32	1
R41	1
R281	1
R421	1
R441 R451	2
U1	1
U2	1
X1	1
X2	1
Total number of components to be mounted	**47**

Description
CAPACITOR, CERAMIC X5R, 2.2uF, 10V, -20%/+20%, -55DEGC/+85DEGC, 0603, SMD
CAPACITORS, CERAMIC, 1uF, 15%, X5R, 10V, 0603, SMD
CAPACITOR, DO NOT MOUNT, 0603, SMD
CAPACITOR, CERAMIC C0G/NP0, 47pF, 50V, -5%/+5%, -55DEGC/+125DEGC, 0402, SMD
CAPACITOR, CERAMIC X5R, 4.7uF, 6.3V, -10%/+10%, -55DEGC/+85DEGC, 0603, SMD
CAPACITOR, CERAMIC X7R, 100nF, 6.3V, -10%/+10%, -55DEGC/+125DEGC, 0402, SMD
CAPACITOR, CERAMIC X7R, 1nF, 50V, -10%/+10%, -55DEGC/+125DEGC, 0402, SMD
CAPACITOR, CERAMIC X5R, 1uF, 10V, -10%/+10%, -55DEGC/+85DEGC, 0402, SMD
CAPACITOR, CERAMIC C0G/NP0, 12pF, 50V, -5%/+5%, -55DEGC/+125DEGC, 0402, SMD
CAPACITOR, CERAMIC C0G/NPO, 18pF, 50V, -55DEGC/+125DEGC, 0402, SMD
CAPACITOR, CERAMIC C0G/NP0, 1pF, 50V, -0.1pF/+0.1pF, -55DEGC/+125DEGC, 0402, SMD
CAPACITOR, CERAMIC C0G/NP0, 1.2pF, 50V, -0.25pF/ +0.25pF, -55DEGC/+125DEGC, 0402, SMD
CAPACITOR, DO NOT MOUNT, 0402, SMD
CAPACITOR, CERAMIC C0G/NP0, 220pF, 50V, -5%/+5%, -55DEGC/+125DEGC, 0402, SMD
CAPACITOR, CERAMIC C0G/NP0, 22pF, 50V, -5%/+5%, -55DEGC/+125DEGC, 0402, SMD
FILTER, EMI, 1500@100MHz, -55DEGC/+125DEGC, 0603, SMD
CONNECTOR, USB-B, 5 PINS, PITCH 0.65mm, SMD
CONNECTOR, COAX RF, DO NOT MOUNT
INDUCTOR, CHIP, 2nH, -0.3nH/ +0.3nH, 0.3A, -55DEGC/+125DEGC, 0402, SMD
INDUCTOR, DO NOT MOUNT, 0402, SMD
INDUCTOR, STANDARD, 3.3nH, -0.3nH/+0.3nH, 0.3A, -55DEGC/+125DEGC, 0402, SMD
CONNECTOR, HEADER, FEMALE, STRAIGHT, 2 ROWS, 20 PINS, PITCH 1.27mm, SMD
CONNECTOR, DO NOT MOUNT, SMD
CONNECTOR, HEADER, STRAIGHT, MALE, 4 PINS, 2 ROWS, 2.54mm PITCH, SMD
CONNECTOR, DO NOT MOUNT
RESISTOR, DO NOT MOUNT, 0402, SMD
RESISTOR, THICK FILM, 33, -1%/+1%, 0.063W, 50V, -55DEGC/+155DEGC, 0402, SMD
RESISTOR, THICK FILM, 1.5k, -1%/+1%, 0.063W, 50V, -55DEGC/+155DEGC, 0402, SMD
RESISTOR, THICK FILM, 2, -1%/+1%, 0.063W, 50V, -55DEGC/+155DEGC, 0402, SMD
RESISTOR, THICK FILM, 2.2k, -1%/+1%, 0.063W, 50V, -55DEGC/+155DEGC, 0402, SMD
RESISTOR, THICK FILM, 56k, -1%/+1%, 0.063W, 50V, -55DEGC/+155DEGC, 0402, SMD
RESISTOR, JUMPER, -55DEGC/+155DEGC, 0402, SMD
IC, ANALOG, ARM CORTEX M3 MCU WITH 2.4GHz IEEE 802.15.4 ZigBee, 2V TO 3.6V, -40DEGC/+125 DEGC, VQFN5
IC, ANALOG, ULTRALOW-POWER LINEAR REGULATORS, VIN:32.7V TO 10V, VOUT: 3.3V, SOT23-5, SMD
CRYSTAL, OSCILATOR, 32MHz, 10pF, -10PPM/+10PPM, -40DEGC/+85DEGC, SMD
CRYSTAL, OSCILATOR, 32.768kHz, -20PPM/ + 20PPM, -40DEGC/ +85DEGC, 12.5pF, SMD

Manufacturer	**Value**	**Part Number**
MURATA	2.2uF	02-01132
MURATA	1uF	02-01389
	DNM	02-01324
MURATA	47pF	02-04366
MURATA	4.7uF	02-02418
MURATA	100nF	02-02323
MURATA	1nF	02-02070
MURATA	1uF	02-02381
MURATA	12pF	02-04168
MURATA	18pF	02-02407
MURATA	1pF	02-04367
MURATA	1.2pF	02-04524
	DNM	02-01321
MURATA	220pF	02-01276
MURATA	22pF	02-04373
MURATA	BLM18HE152SN1	04-00470
Tyco	1981568-1	06-02244
MURATA	2nH	03-06525
	TBD	03-01022
MURATA	3.3nH	03-06501
SAMTEC	SFM-110-02-S-D-A-K-TR	06-02251
GradConn Cable	BB02-HP041-KB3-060B00	06-02190
AMP TYCO ELECTRONICS CORPORATION	826629-2	06-00059
	DNM	01-02475
KOA SPEER	33	01-16853
KOA SPEER	1.5k	01-16854
KOA SPEER	2	01-16855
KOA SPEER	2.2k	01-11503
KOA SPEER	56k	01-16848
KOA SPEER	0	01-01784
TEXAS INSTRUMENTS	CC2538F512RKU	18-27810
TEXAS INSTRUMENTS	TPS76933	18-00550
Epson Toyocom	32MHz	12-00422
Epson Toyocom	32.768kHz	12-00430

MPN	PCB Packa	Rtd Voltage	Min Oper Temp	Max Oper Temp
GRM188R61A225ME34D	0603	10V	-55DEGC	+85DEGC
GRM188R61A105KA61D	0603	10V	-55DEGC	+85DEGC
GRM1555C1H470JA01D	0402	50V	-55DEGC	+125DEGC
GRM188R60J475KE19D	0603	6.3V	-55DEGC	+85DEGC
GRM155R70J104KA01D	0402	6.3V	-55DEGC	+125DEGC
GRM155R71H102KA01D	0402	50V	-55DEGC	+125DEGC
GRM155R61A105KE15D	0402	10V	-55DEGC	+85DEGC
GRM1555C1H120JA01D	0402	50V	-55DEGC	+125DEGC
GRM1555C1H180JA01D	0402	50V	-55DEGC	+125DEGC
GRM1555C1H1R0BA01D	0402	50V	-55DEGC	+125DEGC
GRM1555C1H1R2CA01D	0402	50V	-55DEGC	+125DEGC
GRM1555C1H221JA01D	0402	50V	-55DEGC	+125DEGC
GRM1555C1H220JA01D	0402	50V	-55DEGC	+125DEGC
BLM18HE152SN1D	0603		-55DEGC	+125DEGC
1981568-1			N/A	N/A
LQG15HS2N0S02D	0402		-55DEGC	+125DEGC
LQG15HS3N3S02D	0402		-55DEGC	+125DEGC
SFM-110-02-SM-D-A-K-TR			-55DEGC	+125DEGC
BB02-HP041-KB3-060B00			-40DEGC	+105DEGC
826629-2		750V	-65DEGC	+105DEGC
RK73H1ETTP33R0F	0402	50V	-55DEGC	+155DEGC
RK73H1ETTP1501F	0402	50V	-55DEGC	+155DEGC
RK73H1ETTP2R00F	0402	50V	-55DEGC	+155DEGC
RK73H1ETTP2201F	0402	50V	-55DEGC	+155DEGC
RK73H1ETTP5602F	0402	50V	-55DEGC	+155DEGC
RK73Z1ETTP	0402		-55DEGC	+155DEGC
CC2538F512RKU	VQFN56	2V TO 3.6V	-40DEGC	+125DEGC
TPS76933DBVT	SOT23-5	3.3V	-40DEGC	+125DEGC
FA-128 32MHz 10pF 10PPM	SMD		-40DEGC	+85DEGC
FC-12M 32.768kHz 20ppm			-40DEGC	+85DEGC

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